

# Hardware replacement tips

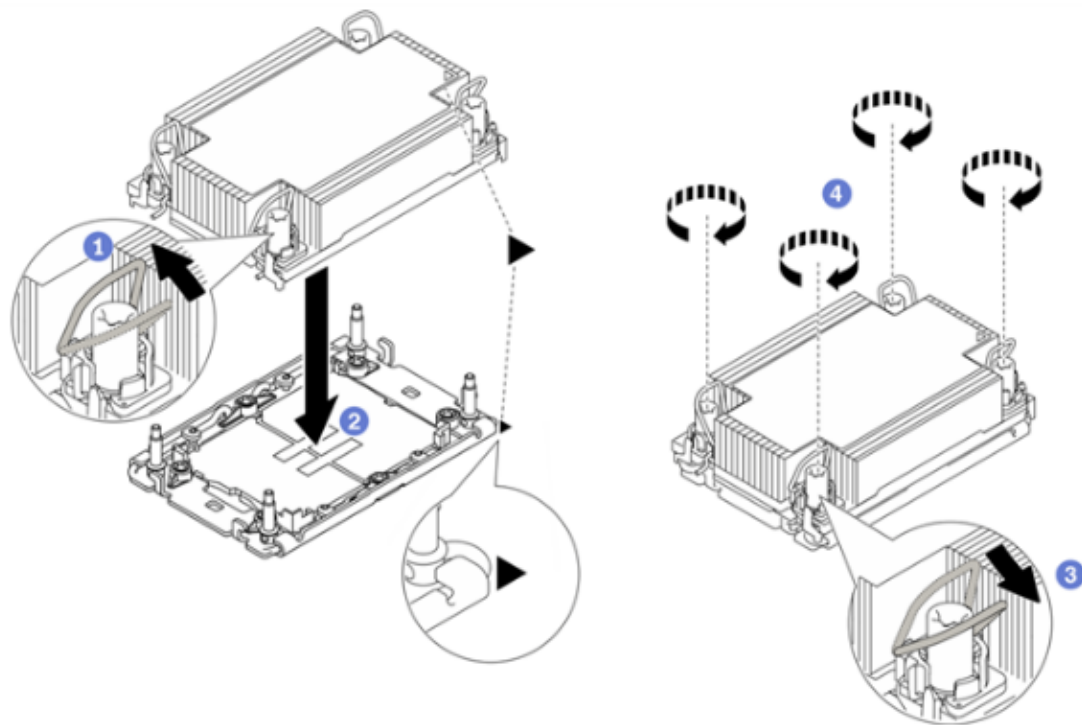
Part replacement highlights

Lenovo

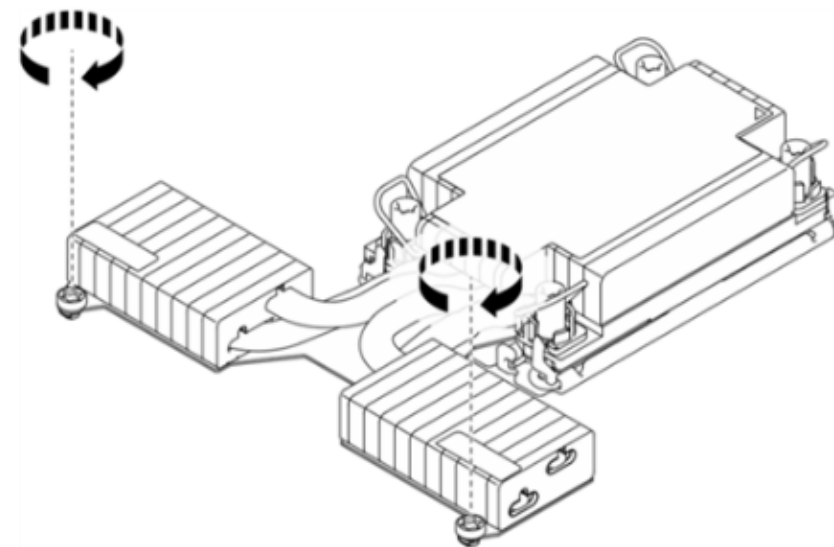
## Replacing a heat sink

The SR630 V3 heat sink replacement procedure requires a Torx T30 torque screwdriver. The SR630 V3 heat sink, processor, and system board FRU are shipped with a Torx T30 bit. Follow the removal sequence instructions and torque settings shown on the heat sink label to remove or install a heat sink. The recommend torque required to fully tighten the heat sink is 0.9-1.3 newton-meters, or 8-12 inch-pounds.

Installing a standard heat sink



Installing a T-shaped heat sink



## Replacing a firmware and RoT security module

After replacing a firmware and RoT security module (RoT module), servicers must update the UEFI and LXPM firmware to the latest supported version before starting the system. If this does not happen, the system will not be able to recognize the correct firmware and will not start normally. As a result, the user will not be able to access the system OS.

Use one of the following methods to update the UEFI and LXPM firmware on the system after replacing the RoT module:

- OneCLI commands
- A USB boot kit with UEFI firmware and LXPM firmware packages
  - For more information on how to create a USB boot kit, refer to the following GLOSSE article:

[How to create USB boot kit with OneCLI for RoT replacement in the field](#)

For the complete procedures, refer to the following GLOSSE tip page:

[How to do RoT Module FW update on ThinkSystem V3 machines](#)

For more information about RoT module, refer to the following course: [ES52374 – ThinkSystem tools for the ThinkSystem V3 platform](#)

## Updating VPD

After replacing a processor board, service personnel must update the VPD on the system board. The SR630 V3 VPD update procedure is the same as that used with Intel-based ThinkSystem models (using the `onecli config set OneCLI` command).

Servicers can also use the XCC tool (for servicers only – not available for customers) to update VPD on a SR630 V3 server.

For more information, refer to the LXCE OneCLI common task section of course [ES51757B Introducing ThinkSystem tools](#) and [ES52374 – ThinkSystem tools for the ThinkSystem V3 platform](#), or the Update the Vital Product Data (VPD) section of the ThinkSystem SR630 V3 User Guide on [Lenovo Support](#).



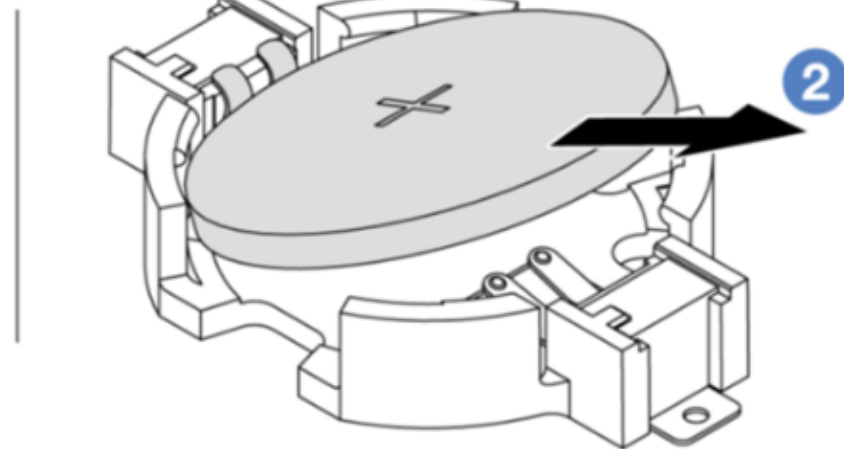
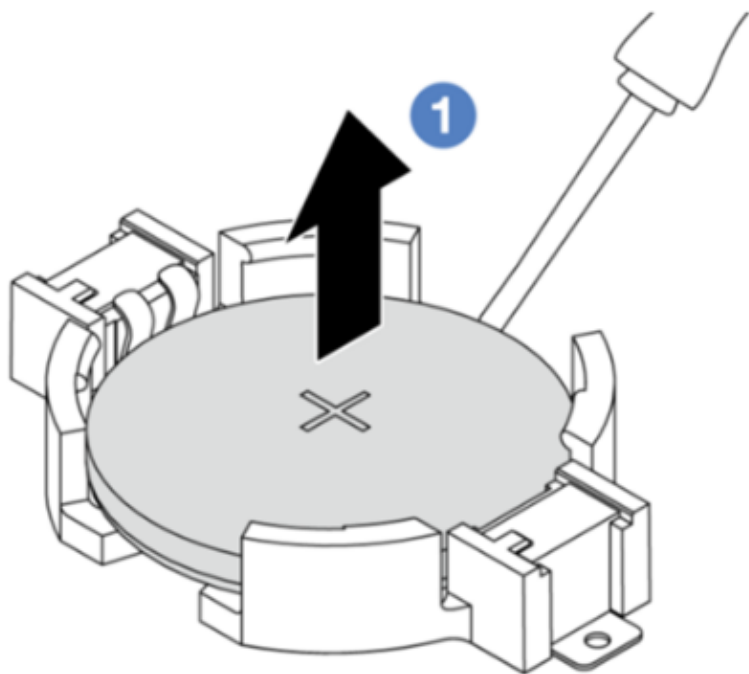
## M.2 drive replacement

To replace M.2 drives and the M.2 adapter, you might need to adjust the retainer on the adapter.



## Removing a CMOS battery

To remove a CMOS battery from the SR630 V3 system board, use a flat blade screwdriver to lever the battery from the socket. Do not use a finger to tilt or push the battery, as it might damage the battery socket. Any damage to the battery socket might result in the entire processor board needing to be replaced.



## Handling a Liquid Assisted Cooling Module

Before replacing the components listed below, check the heat sink in the system to be serviced. If it is a Liquid Assisted Cooling Module (LACM), you will need a module handle (FRU PN: 03KL323, FRU name: Liquid Active Cooling Module bracket). Do NOT attempt to move the LACM with your hands as this could damage the module.

- Processor
- Processor board
- System I/O board



LACM Handle





# Summary

This course enabled you to:

- Describe the features and specifications of the ThinkSystem SR630 V3
- Identify the components of the SR630 V3
- Describe the configurations of the SR630 V3
- Describe the SR630 V3 server management tools
- Describe the specific problem determination steps and explain how to troubleshoot issues with the SR630 V3